

SPECIFICATIONS OF JL-D16



機型	MODEL	JL-D16
研磨盤外徑	Diameter of lapping plate	1127 mm
夾具CARRIER (游星輪)直徑	Diameter of carrier (planetary carrier)	直徑 370 mm DP12, 200齒 DP12, Z200
夾具CARRIER (游星輪)數量	Quantity of carrier (planetary carrier)	5 SETS
每次總加工數量	Total processed quantity	6" 晶圓(Wafer): 15片(pcs) (3pc / carrier) 8" 晶圓(Wafer): 5片(pcs) (1pc / carrier) 12" 晶圓(Wafer): 5片(pcs) (1pc / carrier)
自動厚度控制	Automatic thickness control	可選配 Optional
加壓方式	Pressing method	氣壓缸加壓 Air cylinder pressing
壓力控制方式	Pressure control	電控比例閥 Electronic proportional valve
人機介面	Touchscreen	可選配 Optional
控制方式	Controller	PLC + 人機介面 PLC + Touchscreen
內齒輪轉盤	Internal gear disc	3HP
上磨盤驅動力	Upper plate drive horsepower	5HP
下磨盤驅動力	Lower plate drive horsepower	15HP
盤面轉速	Lapping plate speed	20-60 R.P.M.
磨盤壓力	Pressure on lapping plate	10-300 KG
最大加工厚度	Max. lapping thickness	40 mm
最小加工厚度	Min. lapping thickness	0.4mm
機器尺寸	Machine dimensions	W: 2300 x D: 1420 x H:2550 mm
機器重量	Machine weight	6200 kg
適用電源	Power source	3Ø 220V (3Ø 380V)

DOUBLE-SIDED LAPPING / POLISHING MACHINE

雙面研磨機 / 拋光機



Design and specifications are subject to change without prior notice.



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JL-2022-10-1000EC

JL-D16

Series

機器特性

- 本機適用於平面工件之雙面同時研磨作業。具有高效率、高產能特色，適合大量生產線之精密研磨。
- 研磨後之工件具有優異的平面度、上、下面平行度及表面精度。
- 研磨機構採用游星式運轉設計，達到最佳研磨性能及研磨表面效果。
- 研磨機構可正逆轉。
- 具有5組游星輪夾具，可一次放置多工件同時研磨。
- 壓力控制方式採用電控比例閥控制，提供更穩定的輸出壓力。
- 可依客戶需求增加自動厚度控制功能(選配)。
- 本機操作控制採用PLC控制器，配合使用人機界面面板(選配)，提供操作者簡易的操控性。
- 下研磨盤轉速為無段變速，轉速範圍20~60 rpm。
- 上、下研磨盤與中心齒輪為直結式驅動，確保動作順暢，且傳動精度高。

MACHINE FEATURES

- This machine is suitable for double-sided lapping operations on flat workpieces. With its high efficiency and high productivity, this machine is ideal for precision lapping in a mass production line.
- The lapping process creates outstanding flatness and parallelism between top and bottom surfaces and surface accuracy.
- The lapping mechanism running is designed with a planetary type design to achieve the optimal lapping performance and surface finish.
- The lapping mechanism is able to run clockwise and counter-clockwise.
- 5 sets of carrier (planetary carrier) allow for holding multiple workpieces for lapping simultaneously.
- An electronic proportional valve is used for pressure control, providing increased stability in pressure output.
- Upon customer request, the automatic thickness control is available (optional).
- The machine is equipped with a PLC controller in combination with the use of the touchscreen (optional), providing user-friendly operation.
- The running speed of the lower plate is variable, with a range of 20~60 RPM.
- The upper / lower plates and the center gear are driven directly, ensuring smooth motions and high transmission accuracy.



適合研磨工件種類

本機可應用於各種材質之平面工件之研磨，包括半導體材料及各種金屬、非金屬、鋁材、不鏽鋼、陶瓷等。

APPLICABLE PART MATERIALS FOR LAPPING

This machine is applicable for lapping various materials of flat workpiece, such as semiconductor materials and various metals, non-metals, aluminum, stainless steel, and ceramics.

研磨 Lapping



石英 Crystal

拋光 Polishing



光學玻璃 Optical Glass



碳化矽 SiC

石英 Crystal



矽晶圓 Silicon Wafer

石英玻璃 Crystal Glass